

Atmel Corporation - Package Material Declaration Datasheet			
Package Description	64-Lead, 14.0 x 14.0 x 1.0 mm Body, 0.80 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)		
Package Code	64A	GPC	ADY
Lead Finish	Matte Tin (Sn)	RoHS Compliant	Yes
J-STD-609 Category	e3	Green Compliant	Yes
Assembly Location	ASE Kaohsiung	REACH Compliant	Yes

Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Leadframe	Copper (Cu)	7440-50-8	131.770	96.2	962000	25.41	254074
	Nickel (Ni)	7440-02-0	4.109	3.0	30000	0.79	7923
	Silicon (Si)	7440-21-3	0.822	0.6	6000	0.16	1585
	Magnesium (Mg)	7439-95-4	0.274	0.2	2000	0.05	528
<b>Sub-Total</b>			<b>136.975</b>	<b>100.0</b>	<b>1000000</b>	<b>26.41</b>	<b>264110</b>
Integrated Circuit	Silicon (Si)	7440-21-3	11.981	100.0	1000000	2.31	23102
<b>Sub-Total</b>			<b>11.981</b>	<b>100.0</b>	<b>1000000</b>	<b>2.31</b>	<b>23102</b>
Die Attach	Silver (Ag)	7440-22-4	0.730	86.3	863000	0.14	1408
	2-Propenoic Acid, Dodecyl Ester	2156-97-0	0.036	4.3	43000	0.01	70
	Dicyclopentylidimethylene Diacrylate	42594-17-2	0.033	3.9	39000	0.01	64
	Diglycidylphenyl Glycidyl Ether	13561-08-5	0.033	3.9	39000	0.01	64
	Bis(.alpha.,.alpha.-Dimethylbenzyl) Peroxide	80-43-3	0.007	0.8	8000	0.00	13
	Isobornyl Methacrylate	7534-94-3	0.007	0.8	8000	0.00	13
<b>Sub-Total</b>			<b>0.846</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1631</b>
Die Pad Plating	Silver (Ag)	7440-22-4	1.210	100.0	1000000	0.23	2333
<b>Sub-Total</b>			<b>1.210</b>	<b>100.0</b>	<b>1000000</b>	<b>0.23</b>	<b>2333</b>
Bond Wire	Gold (Au)	7440-57-5	0.647	100.0	1000000	0.12	1248
<b>Sub-Total</b>			<b>0.647</b>	<b>100.0</b>	<b>1000000</b>	<b>0.12</b>	<b>1248</b>
Encapsulation	Silica Fused	60676-86-0	310.047	86.4	864000	59.78	597823
	Epoxy Resin	Proprietary	28.349	7.9	79000	5.47	54662
	Phenol Resin	Proprietary	19.378	5.4	54000	3.74	37364
	Carbon Black	1333-86-4	1.077	0.3	3000	0.21	2076
<b>Sub-Total</b>			<b>358.851</b>	<b>100.0</b>	<b>1000000</b>	<b>69.19</b>	<b>691925</b>
Terminal Plating	Tin (Sn)	7440-31-5	8.117	100.0	1000000	1.57	15651
<b>Sub-Total</b>			<b>8.117</b>	<b>100.0</b>	<b>1000000</b>	<b>1.57</b>	<b>15651</b>
<b>Total</b>			<b>518.627</b>			<b>100.00</b>	<b>1000000</b>

**Package Material Declaration Certificate**

Atmel Corporation certifies that the material content information provided above is representative and accurate as of the date of this declaration. Atmel Corporation products designated as "RoHS Compliant" or "Green" (defined below) do not exceed the threshold limits of the European Union Restriction of Hazardous Substances (RoHS) Directive 2011/65/EU, and the China Administration on Control of Pollution by Electronic Information Products (China RoHS).

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Name / Title: William B. Dupey III / Quality Engineer & Chemist

Date: March 20, 2015



**RoHS Compliant:** Atmel Corporation defines "RoHS Compliant" to mean maximum concentration value of 0.1% (1000 ppm) for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr+6), Polybrominated Biphenyl (PBB), Polybrominated Diphenyl Ether (PBDE) and maximum concentration value of 0.01% (100 ppm) for Cadmium (Cd) in any homogeneous material.

**Green:** Atmel Corporation defines "Green" to mean, in addition to substances listed in "RoHS Compliant", maximum concentration value of 0.09% (900 ppm) for Antimony (Sb), 0.09% (900 ppm) for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1500 ppm) total Bromine (Br) and Chlorine (Cl) in any homogeneous material.

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Package Description	64-Lead, 14.0 x 14.0 x 1.0 mm Body, 0.80 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)		
Package Code	64A	GPC	ADY
Lead Finish	Matte Tin (Sn)	RoHS Compliant	Yes
J-STD-609 Category	e3	Green Compliant	Yes
Assembly Location	Amkor Korea / Amkor Philippines	REACH Compliant	Yes

Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Leadframe	Copper (Cu)	7440-50-8	137.249	99.3	993000	26.40	264010
	Chromium (Cr)	7440-47-3	0.415	0.3	3000	0.08	798
	Tin (Sn)	7440-31-5	0.276	0.2	2000	0.05	532
	Zinc (Zn)	7440-66-6	0.276	0.2	2000	0.05	532
<b>Sub-Total</b>			<b>138.217</b>	<b>100.0</b>	<b>1000000</b>	<b>26.59</b>	<b>265871</b>
Integrated Circuit	Silicon (Si)	7440-21-3	11.981	100.0	1000000	2.30	23047
<b>Sub-Total</b>			<b>11.981</b>	<b>100.0</b>	<b>1000000</b>	<b>2.30</b>	<b>23047</b>
Die Attach	Silver (Ag)	7440-22-4	0.609	72.4	724000	0.12	1172
	Bisphenol F Diglycidyl Ether	39817-09-9	0.050	5.9	59000	0.01	95
	1,4-Bis(2,3-Epoxypropoxy)Butane	2425-79-8	0.042	5.0	50000	0.01	81
	2,6-Diglycidyl Phenyl Allyl Ether Oligomer	Proprietary	0.042	5.0	50000	0.01	81
	Dihydro-3-(Tetrapropenyl)Furan-2,5-Dione	26544-38-7	0.038	4.5	45000	0.01	73
	Oxirane, 2-Dodecyl-	3234-28-4	0.038	4.5	45000	0.01	73
	Methylhexahydrophthalic Anhydride	19438-60-9	0.023	2.7	27000	0.00	44
<b>Sub-Total</b>			<b>0.841</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1619</b>
Die Pad Plating	Silver (Ag)	7440-22-4	1.210	100.0	1000000	0.23	2328
<b>Sub-Total</b>			<b>1.210</b>	<b>100.0</b>	<b>1000000</b>	<b>0.23</b>	<b>2328</b>
Bond Wire	Gold (Au)	7440-57-5	0.647	100.0	1000000	0.12	1245
<b>Sub-Total</b>			<b>0.647</b>	<b>100.0</b>	<b>1000000</b>	<b>0.12</b>	<b>1245</b>
Encapsulation	Silica Fused	60676-86-0	310.047	86.4	864000	59.64	596400
	Epoxy Resin	Proprietary	28.349	7.9	79000	5.45	54532
	Phenol Resin	Proprietary	19.378	5.4	54000	3.73	37275
	Carbon Black	1333-86-4	1.077	0.3	3000	0.21	2071
<b>Sub-Total</b>			<b>358.851</b>	<b>100.0</b>	<b>1000000</b>	<b>69.03</b>	<b>690277</b>
Terminal Plating	Tin (Sn)	7440-31-5	8.117	100.0	1000000	1.56	15614
<b>Sub-Total</b>			<b>8.117</b>	<b>100.0</b>	<b>1000000</b>	<b>1.56</b>	<b>15614</b>
<b>Total</b>			<b>519.865</b>			<b>100.00</b>	<b>1000000</b>

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Name / Title: William B. Dupey III / Quality Engineer & Chemist

Date: March 20, 2015



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**Green:** Atmel Corporation defines "Green" to mean, in addition to substances listed in "RoHS Compliant", maximum concentration value of 0.09% (900 ppm) for Antimony (Sb), 0.09% (900 ppm) for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1500 ppm) total Bromine (Br) and Chlorine (Cl) in any homogeneous material.

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Package Description	64-Lead, 14.0 x 14.0 x 1.0 mm Body, 0.80 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)		
Package Code	64A	GPC	ADY
Lead Finish	Matte Tin (Sn)	RoHS Compliant	Yes
J-STD-609 Category	e3	Green Compliant	Yes
Assembly Location	Lingsen	REACH Compliant	Yes

Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Leadframe	Copper (Cu)	7440-50-8	131.770	96.2	962000	25.41	254088
	Nickel (Ni)	7440-02-0	4.109	3.0	30000	0.79	7924
	Silicon (Si)	7440-21-3	0.822	0.6	6000	0.16	1585
	Magnesium (Mg)	7439-95-4	0.274	0.2	2000	0.05	528
<b>Sub-Total</b>			<b>136.975</b>	<b>100.0</b>	<b>1000000</b>	<b>26.41</b>	<b>264124</b>
Integrated Circuit	Silicon (Si)	7440-21-3	11.981	100.0	1000000	2.31	23103
<b>Sub-Total</b>			<b>11.981</b>	<b>100.0</b>	<b>1000000</b>	<b>2.31</b>	<b>23103</b>
Die Attach	Silver (Ag)	7440-22-4	0.590	72.1	721000	0.11	1137
	Epoxy Resin	9003-36-5	0.160	19.5	195000	0.03	308
	t-Butyl Phenyl Glycidyl Ether	3101-60-8	0.053	6.5	65000	0.01	103
	Butyl Cellosolve Acetate	112-07-2	0.007	0.8	8000	0.00	13
	Phenolic Resin	92-88-6	0.007	0.8	8000	0.00	13
	Dicyandiamide	461-58-5	0.002	0.3	3000	0.00	5
<b>Sub-Total</b>			<b>0.818</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1577</b>
Die Pad Plating	Silver (Ag)	7440-22-4	1.210	100.0	1000000	0.23	2334
<b>Sub-Total</b>			<b>1.210</b>	<b>100.0</b>	<b>1000000</b>	<b>0.23</b>	<b>2334</b>
Bond Wire	Gold (Au)	7440-57-5	0.647	100.0	1000000	0.12	1248
<b>Sub-Total</b>			<b>0.647</b>	<b>100.0</b>	<b>1000000</b>	<b>0.12</b>	<b>1248</b>
Encapsulation	Silica Fused	60676-86-0	310.047	86.4	864000	59.79	597855
	Epoxy Resin	Proprietary	28.349	7.9	79000	5.47	54665
	Phenol Resin	Proprietary	19.378	5.4	54000	3.74	37366
	Carbon Black	1333-86-4	1.077	0.3	3000	0.21	2076
<b>Sub-Total</b>			<b>358.851</b>	<b>100.0</b>	<b>1000000</b>	<b>69.20</b>	<b>691962</b>
Terminal Plating	Tin (Sn)	7440-31-5	8.117	100.0	1000000	1.57	15652
<b>Sub-Total</b>			<b>8.117</b>	<b>100.0</b>	<b>1000000</b>	<b>1.57</b>	<b>15652</b>
<b>Total</b>			<b>518.599</b>			<b>100.00</b>	<b>1000000</b>

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Date: March 20, 2015



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**Green:** Atmel Corporation defines "Green" to mean, in addition to substances listed in "RoHS Compliant", maximum concentration value of 0.09% (900 ppm) for Antimony (Sb), 0.09% (900 ppm) for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1500 ppm) total Bromine (Br) and Chlorine (Cl) in any homogeneous material.

Atmel Corporation - Package Material Declaration Datasheet			
Package Description	64-Lead, 14.0 x 14.0 x 1.0 mm Body, 0.80 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)		
Package Code	64A	GPC	ADY
Lead Finish	Matte Tin (Sn)	RoHS Compliant	Yes
J-STD-609 Category	e3	Green Compliant	Yes
Assembly Location	ASE Kaohsiung	REACH Compliant	Yes

Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Leadframe	Copper (Cu)	7440-50-8	131.770	96.2	962000	25.43	254257
	Nickel (Ni)	7440-02-0	4.109	3.0	30000	0.79	7929
	Silicon (Si)	7440-21-3	0.822	0.6	6000	0.16	1586
	Magnesium (Mg)	7439-95-4	0.274	0.2	2000	0.05	529
<b>Sub-Total</b>			<b>136.975</b>	<b>100.0</b>	<b>1000000</b>	<b>26.43</b>	<b>264300</b>
Integrated Circuit	Silicon (Si)	7440-21-3	11.981	100.0	1000000	2.31	23118
<b>Sub-Total</b>			<b>11.981</b>	<b>100.0</b>	<b>1000000</b>	<b>2.31</b>	<b>23118</b>
Die Attach	Silver (Ag)	7440-22-4	0.611	74.7	747000	0.12	1179
	Epoxy Resin B	Proprietary	0.048	5.9	59000	0.01	93
	Diluent B	Proprietary	0.048	5.9	59000	0.01	93
	Hardener	Proprietary	0.040	4.9	49000	0.01	77
	Epoxy Resin A	9003-36-5	0.032	3.9	39000	0.01	62
	Diluent A	Proprietary	0.032	3.9	39000	0.01	62
	Organic Peroxide	Proprietary	0.004	0.5	5000	0.00	8
	Dicyandiamide	461-58-5	0.002	0.3	3000	0.00	5
<b>Sub-Total</b>			<b>0.818</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1579</b>
Die Pad Plating	Silver (Ag)	7440-22-4	1.210	100.0	1000000	0.23	2335
<b>Sub-Total</b>			<b>1.210</b>	<b>100.0</b>	<b>1000000</b>	<b>0.23</b>	<b>2335</b>
Bond Wire	Copper (Cu)	7440-50-8	0.294	97.6	976000	0.06	568
	Palladium (Pd)	7440-05-3	0.007	2.4	24000	0.00	14
<b>Sub-Total</b>			<b>0.302</b>	<b>100.0</b>	<b>1000000</b>	<b>0.06</b>	<b>582</b>
Encapsulation	Silica Fused	60676-86-0	274.521	76.5	765000	52.97	529704
	Silica Fused	76361-86-9	38.756	10.8	108000	7.48	74782
	Phenol Resin	Proprietary	19.737	5.5	55000	3.81	38083
	Epoxy Resin A	Proprietary	11.842	3.3	33000	2.28	22850
	Epoxy Resin B	Proprietary	11.842	3.3	33000	2.28	22850
	Carbon Black	1333-86-4	1.077	0.3	3000	0.21	2077
	Silica, Crystalline	14808-60-7	1.077	0.3	3000	0.21	2077
<b>Sub-Total</b>			<b>358.851</b>	<b>100.0</b>	<b>1000000</b>	<b>69.24</b>	<b>692423</b>
Terminal Plating	Tin (Sn)	7440-31-5	8.117	100.0	1000000	1.57	15662
<b>Sub-Total</b>			<b>8.117</b>	<b>100.0</b>	<b>1000000</b>	<b>1.57</b>	<b>15662</b>
<b>Total</b>			<b>518.253</b>			<b>100.00</b>	<b>1000000</b>

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Package Code	64A	GPC	ADY
Lead Finish	Matte Tin (Sn)	RoHS Compliant	Yes
J-STD-609 Category	e3	Green Compliant	Yes
Assembly Location	Amkor Philippines	REACH Compliant	Yes

Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Leadframe	Copper (Cu)	7440-50-8	137.249	99.3	993000	26.42	264186
	Chromium (Cr)	7440-47-3	0.415	0.3	3000	0.08	798
	Tin (Sn)	7440-31-5	0.276	0.2	2000	0.05	532
	Zinc (Zn)	7440-66-6	0.276	0.2	2000	0.05	532
<b>Sub-Total</b>			<b>138.217</b>	<b>100.0</b>	<b>1000000</b>	<b>26.60</b>	<b>266048</b>
Integrated Circuit	Silicon (Si)	7440-21-3	11.981	100.0	1000000	2.31	23062
<b>Sub-Total</b>			<b>11.981</b>	<b>100.0</b>	<b>1000000</b>	<b>2.31</b>	<b>23062</b>
Die Attach	Silver (Ag)	7440-22-4	0.609	72.4	724000	0.12	1173
	Bisphenol F Diglycidyl Ether	39817-09-9	0.050	5.9	59000	0.01	96
	1,4-Bis(2,3-Epoxypropoxy)Butane	2425-79-8	0.042	5.0	50000	0.01	81
	2,6-Diglycidyl Phenyl Allyl Ether Oligomer	Proprietary	0.042	5.0	50000	0.01	81
	Dihydro-3-(Tetrapropenyl)Furan-2,5-Dione	26544-38-7	0.038	4.5	45000	0.01	73
	Oxirane, 2-Dodecyl-	3234-28-4	0.038	4.5	45000	0.01	73
	Methylhexahydrophthalic Anhydride	19438-60-9	0.023	2.7	27000	0.00	44
<b>Sub-Total</b>			<b>0.841</b>	<b>100.0</b>	<b>1000000</b>	<b>0.16</b>	<b>1620</b>
Die Pad Plating	Silver (Ag)	7440-22-4	1.210	100.0	1000000	0.23	2329
<b>Sub-Total</b>			<b>1.210</b>	<b>100.0</b>	<b>1000000</b>	<b>0.23</b>	<b>2329</b>
Bond Wire	Copper (Cu)	7440-50-8	0.294	97.6	976000	0.06	567
	Palladium (Pd)	7440-05-3	0.007	2.4	24000	0.00	14
<b>Sub-Total</b>			<b>0.302</b>	<b>100.0</b>	<b>1000000</b>	<b>0.06</b>	<b>581</b>
Encapsulation	Silica Fused	60676-86-0	310.047	86.4	864000	59.68	596796
	Epoxy Resin	Proprietary	28.349	7.9	79000	5.46	54568
	Phenol Resin	Proprietary	19.378	5.4	54000	3.73	37300
	Carbon Black	1333-86-4	1.077	0.3	3000	0.21	2072
<b>Sub-Total</b>			<b>358.851</b>	<b>100.0</b>	<b>1000000</b>	<b>69.07</b>	<b>690736</b>
Terminal Plating	Tin (Sn)	7440-31-5	8.117	100.0	1000000	1.56	15624
<b>Sub-Total</b>			<b>8.117</b>	<b>100.0</b>	<b>1000000</b>	<b>1.56</b>	<b>15624</b>
<b>Total</b>			<b>519.519</b>			<b>100.00</b>	<b>1000000</b>

### Package Material Declaration Certificate

Atmel Corporation certifies that the material content information provided above is representative and accurate as of the date of this declaration. Atmel Corporation products designated as "RoHS Compliant" or "Green" (defined below) do not exceed the threshold limits of the European Union Restriction of Hazardous Substances (RoHS) Directive 2011/65/EU, and the China Administration on Control of Pollution by Electronic Information Products (China RoHS).

Atmel Corporation has taken commercially reasonable steps to provide representative and accurate information, but may not have conducted chemical analysis or destructive testing on incoming materials. Atmel Corporation and its suppliers consider certain information to be proprietary and thus CAS numbers and other limited information may not be available for release. Atmel Corporation accepts no duty to notify or update users of any changes made to this declaration. Atmel Corporation's standard Terms and Conditions apply to the representations provided herein unless otherwise provided by a written contract or other agreement signed by both parties.

Name / Title: William B. Dupey III / Quality Engineer & Chemist

Date: March 20, 2015



**RoHS Compliant:** Atmel Corporation defines "RoHS Compliant" to mean maximum concentration value of 0.1% (1000 ppm) for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr+6), Polybrominated Biphenyl (PBB), Polybrominated Diphenyl Ether (PBDE) and maximum concentration value of 0.01% (100 ppm) for Cadmium (Cd) in any homogeneous material.

**Green:** Atmel Corporation defines "Green" to mean, in addition to substances listed in "RoHS Compliant", maximum concentration value of 0.09% (900 ppm) for Antimony (Sb), 0.09% (900 ppm) for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1500 ppm) total Bromine (Br) and Chlorine (Cl) in any homogeneous material.